

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Before Application of

Alexander T. SCHWARM

Serial No. 10/765,921

Filed: January 29, 2004

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: Group Art Unit:
:
: Examiner:

For: **SYSTEM, METHOD, AND MEDIUM FOR MONITORING PERFORMANCE OF AN
ADVANCED PROCESS CONTROL SYSTEM**

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of any cited U.S. Patents and U.S. Patent Publications are not being submitted in accordance with 37 CFR 1.98(a)(2)(i).

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of

publication indicated for an item is taken from the face of the item, and Applicant reserves the right to prove that the date of publication is in fact different.

The references listed on Sheet 1 of the attached PTO-1449 Forms were cited in a patentability investigation and/or a corresponding foreign or PCT application relating to the above-referenced application. The remaining references are from potentially related patent applications, and possibly other sources.

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

WILMER CUTLER PICKERING HALE AND DORR LLP



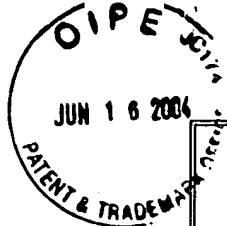
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Date: 6/16/04

INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION
(PTO-1449)ATTY. DOCKET NO.
007733 USA/FPS/MMCS/APCSERIAL NO.
10/765,921APPLICANT
Alexander T. SCHWARMFILING DATE
January 29, 2004

GROUP

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,642,296	06/24/97	Saxena			07/29/93
	5,646,870	07/08/97	Krivokapic et al.			02/13/95
	5,719,796	02/17/98	Chen			12/04/95
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	WO 01/25865 A1	04/12/01	WO			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	Chang, Norman H. and Costas J. Spanos. February 1991. "Continuous Equipment Diagnosis Using Evidence Integration: An LPCVD Application." <i>IEEE Transactions on Semiconductor Manufacturing</i> , v. 4, n. 1, pp. 43-51.
	Boning, Duane S., Jerry Stefani, and Stephanie W. Butler. February 1999. "Statistical Methods for Semiconductor Manufacturing." <i>Encyclopedia of Electrical Engineering</i> , J. G. Webster, Ed.
	"Semiconductor Manufacturing: An Overview." < http://users.ece.gatech.edu/~gmay/overview.html >
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	3,205,485	09/07/65	Noltingk			10/21/60	
	3,229,198	01/11/66	Libby			09/28/62	
	3,767,900	10/23/73	Chao et al.			06/23/71	
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U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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	<p>APPLICANT Alexander T. SCHWARM</p>	
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FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	61-66104 ✓	04/04/86	Japan			X	
	61-171147	08/01/86	Japan			X	
	01-283934	11/15/89	Japan			X	
	0 397 924 A1	11/22/90	Europe			X	
	2,050,247 ✓	08/29/91	Canada			X	
	2,165,847 ✓	08/29/91	Canada			X	
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	3-202710 ✓	09/04/91	Japan			X	
	05-151231 ✓	06/18/93	Japan			X	
	05-216896 ✓	08/27/93	Japan			X	
	05-266029 ✓	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
	06-184434 ✓	07/05/94	Japan			X	
	06-252236 ✓	09/09/94	Japan			X	
	06-260380 ✓	09/16/94	Japan			X	
	EP 0 621 522 A2 ✓	10/26/94	Europe			X	
	WO 95/34866 ✓	12/21/95	WO			X	
	8-23166 ✓	01/23/96	Japan			X	
	08-50161 ✓	02/20/96	Japan			X	
	08-149583 ✓	06/07/96	Japan			X	
	08-304023	11/22/96	Japan			X	
	EP 0 747 795 A2 ✓	12/11/96	Europe			X	
	09-34535 ✓	02/07/97	Japan			X	
	9-246547	09/19/97	Japan			X	
	WO 98/05066	02/05/98	WO			X	
	10-34522	02/10/98	Japan			X	
	10-173029 ✓	06/26/98	Japan			X	
EXAMINER				DATE CONSIDERED			

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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 007733 USA/FPS/MMCS/APC		SERIAL NO. 10/765,921	
				APPLICANT Alexander T. SCHWARM			
				FILING DATE January 29, 2004		GROUP	
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	EP 0 869 652 A2	10/07/98	Europe			X	
	WO 98/45090	10/15/98	WO			X	
	EP 0 877 308 A2	11/11/98	Europe			X	
	EP 0 881 040 A2	12/02/98	Europe			X	
	EP 0 895 145 A1	02/03/99	Europe			X	
	WO 99/09371	02/25/99	WO			X	
	11-67853	03/09/99	Japan			X	
	EP 0 910 123 A1	04/21/99	Europe			X	
	11-126816	05/11/99	Japan			X	
	11-135601	05/21/99	Japan			X	
	WO 99/25520	05/27/99	WO			X	
	EP 0 932 194 A1	07/28/99	Europe			X	
	WO 99/59200	11/18/99	WO			X	
	WO 00/00874	01/06/00	WO			X	
	WO 00/05759	02/03/00	WO			X	
	WO 00/35063	06/15/00	WO			X	
	2000-183001	06/30/00	Japan			X	
	WO 00/54325	09/14/00	WO			X	
	GB 2 347 885 A	09/20/00	United Kingdom			X	
	WO 00/79355 A1	12/28/00	WO			X	
	EP 1 066 925 A2	01/10/01	Europe			X	
	EP 1 067 757 A1	01/10/01	Europe			X	
	EP 1 071 128 A2	01/24/01	Europe			X	
	WO 01/11679 A1	02/15/01	WO			X	
	WO 01/15865 A1	03/08/01	WO			X	
	WO 01/18623 A1	03/15/01	WO			X	
EXAMINER				DATE CONSIDERED			

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FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	2001-76982	03/23/01	Japan			X	
	EP 1 092 505 A2	04/18/01	Europe			X	
	WO 01/33277 A1	05/10/01	WO			X	
	WO 01/33501 A1	05/10/01	WO			X	
	434103	05/16/01	Taiwan			X	
	436383B	05/28/01	Taiwan			X	
	WO 01/52055 A3	07/19/01	WO			X	
	WO 01/52319 A1	07/19/01	WO			X	
	WO 01/57823 A2	08/09/01	WO			X	
	455938B	09/21/01	Taiwan			X	
	455976	09/21/01	Taiwan			X	
	2001-284299	10/12/01	Japan			X	
	WO 01/80306 A2	10/25/01	WO			X	
	2001-305108	10/31/01	Japan			X	
	EP 1 072 967 A3	11/21/01	Europe			X	
	2002-9030	01/11/02	Japan			X	
	EP 1 182 526 A2	02/27/02	Europe			X	
	WO 02/17150 A1	02/28/02	WO			X	
	WO 02/31613 A2	04/18/02	WO			X	
	WO 02/31613 A3	04/18/02	WO			X	
	WO 02/33737 A2	04/25/02	WO			X	
	WO 02/074491 A1	09/26/02	WO			X	
	2002-343754	11/29/02	Japan			X	
EXAMINER				DATE CONSIDERED			

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